ASSOCIATION CONNECTINI ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				rials and M	ials and Mfg Information				
upplier Inform	ation						·							
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
nsemi										2025-09-15				
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewa	ırds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Iter		m Number Mfr Item Name				Effective Dat	e Versio	Version Manufacturing Site			Weight*	UOM	Unit Type
		FDMS86	DMS86263P FET -150V 53.0 i		nOhm PQFN5	56	2025-09-15 PBB		PBB		104.0	mg	Each	
	Proccess Informati							·					·	·
8 · · · · · · · · · · · · · · · · · · ·			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temper			1.		ture Numb	per of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy			U Alloy	1			260		C	30	secon	ids 3		
omments														
vel 1 - maximum t	ime at peak temperatur	e during sol	dering is 10-3	30 seconds										
or more informatio	on regarding material co	omposition j	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.09	mg	Supplier	Silicon (Si)	7440-21-3		5.09	mg
Die Attach Solder	3.92	mg	Supplier	Silver (Ag)	7440-22-4		0.098	mg
			A	Lead (Pb)	7439-92-1	7a	3.626	mg
			Supplier	Tin (Sn)	7440-31-5		0.196	mg
Lead Frame	44.88		Supplier	Silver (Ag)	7440-22-4		0.1346	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0539	mg
			Supplier	Iron (Fe)	7439-89-6		1.0547	mg
			Supplier	Copper (Cu)	7440-50-8		43.6234	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0135	mg
Mold Compound-Black	47.25			Epoxy resin	proprietary data		6.2843	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0945	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.8713	mg
Plating	0.445	mg	Supplier	Tin (Sn)	7440-31-5		0.445	mg
Wire Bond - Al	2.361	mg	Supplier	Aluminum (Al)	7429-90-5		2.361	mg
Wire Bond - Cu	0.054	mg	Supplier	Copper (Cu)	7440-50-8		0.054	mg